IPC ASSOCIATION CONNECTINE ELECTRONICS INDUSTRIE	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and Mf	ials and Mfg Information			
upplier Inforn														
Company name*			Company unique ID			τ	Unique ID Authority				Response Date*			
onsemi											2024-05-22			
Contact Name		7	Title - Contact			1	Phone - Contact*				Email - Contact*			
Product-Env-Stewa	ards	F	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			1	Phone - Representative*				Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Requesto	Requester Item Number Mfr Ite		em Number Mfr Item Name				Effective Date	Versio	on :	Manufacturing Site		/eight*	UOM	Unit Type
		NVMFS5C442NAFT1 T6-D3F 40V NFET G-YE		T		2024-05-22	22 MYE		1	07.2528	mg	Each		
<b>Ianufacturing</b>	Process Information	n												
Terminal Plating / Grid Array Material			Terminal Base Alloy J-STD-020 MSI		L Rating	Peak Process Body Temperature   Max Time at F		re Max Time at Peak	Temperatu	re Numb	er of Reflow Cyc	eles		
Matte Tin (Sn) - annealed		CU	CU Alloy 1				260		С	30	second	s <b>3</b>		
omments														
vel 1 - maximum t	ime at peak temperature	during solde	ering is 10-30	0 seconds										
or more informati	on regarding material con	nposition ple	ease refer to	page 3										<del>-</del>

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Isability and the Company's remedies for issues that arise regarding information the Supplier provides in this fo											
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-En									

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	13.512	mg	Supplier	Iron (Fe)	7439-89-6		0.0135	mg
			Supplier	Copper (Cu)	7440-50-8		13.4944	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0041	mg
Die	0.727	mg	Supplier	Silicon (Si)	7440-21-3		0.727	mg
Die Attach Solder	1.4993	mg	Supplier	Silver (Ag)	7440-22-4		0.0375	mg
			A	Lead (Pb)	7439-92-1	7a	1.3869	mg
			Supplier	Tin (Sn)	7440-31-5		0.075	mg
Lead Frame	42.327103	mg	Supplier	Zinc (Zn)	7440-66-6		0.0508	mg
			Supplier	Iron (Fe)	7439-89-6		0.9947	mg
			Supplier	Copper (Cu)	7440-50-8		41.2689	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0127	mg
Lead Frame plating	0.212699	mg	Supplier	Silver (Ag)	7440-22-4		0.2127	mg
Mold Compound-Black	48.7198	mg		Epoxy resin	proprietary data		3.654	mg
			Supplier	Phenolic Resin	Proprietary Data		1.218	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.654	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2436	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		39.9502	mg
Plating	0.2183	mg	Supplier	Tin (Sn)	7440-31-5		0.2183	mg
Wire Bond - Cu	0.0366	mg	Supplier	Copper (Cu)	7440-50-8		0.0366	mg